



GCS-NSP75 NON SILICONE THERMAL PUTTY

GCS-NSP75 is a dispensible non silicone thermal putty

Features

- High compressibility
- Pump out resistance
- Good adhesion
- Long term stability
- Siloxane Volatiles D4~D20 0%

Configurations



PART NUMBER	Package size
GCS-NSP75-50ml	50ml syringe

Properties

CHARACTERISTIC	TEST METHOD	VALUE
Colour	Visual	Grey
Thermal conductivity W/m K	ASTM D5470	7.5
Density g/cm ³	ASTM D792	3.0
Application temperature (deg C)	ASTM D5470	-40 to +125
Bond line thickness, typical min, mm	ASTM D374	0.05
Dielectric breakdown, kV/mm	ASTM D419	>5
Flow rate (g/min), 90psi/2mm nozzle @ 25degC		5.3
Volume resistivity (Ohms.cm)	ASTM D257	> 10 ¹¹
Durability, high storage baking, (hrs)	JESD22-A103	1000



✉ info@gcsthermal.com

GCS UK Ltd
7 Priory Business Park
Kibworth, Leicestershire
LE8 ORX, UK